

Special Issue

Millimeter-Wave and Terahertz Technology

Message from the Guest Editors

The advances in silicon-based integration technology and the improvement of the HEMT process, with a higher machining accuracy and 2DEG density, make high-performance terahertz detection arrays and transceiver systems achievable, and enable a variety of interesting and valuable applications. This Special Issue aims to demonstrate recent progress in detectors, antennas, and transceiver circuits based on silicon/HEMT/MEMS technologies, and on arrays for security imaging, non-destructive inspection applications, etc

- millimeter-wave and terahertz arrays for security imaging systems
- millimeter-wave and terahertz radar for industrial applications
- millimeter-wave and terahertz solid-state power amplifiers
- waveguide antenna array beyond W-band
- high-sensitivity terahertz receiving chains and systems

Guest Editors

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Deadline for manuscript submissions

closed (31 October 2022)



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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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